## 502701668 02/28/2014

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:		NEW ASSIG	NMENT		
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NATURE OF CONVEYANCE:		ASSIGNMEN	ASSIGNMENT		
CONVEYING PARTY	/ DATA				
		Name		Execution Date	
HIROSHI INOUE				02/10/2014	
AKIO KATSUMATA				02/10/2014	
SHIGENORI SAWACHI				02/10/2014	
OSAMU YAMAGATA				02/10/2014	
RECEIVING PARTY	DATA				
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		USUKI-SHI, OITA			
City: State/Country:	<b></b>	JAPAN			
,					
PROPERTY NUMBE	RS Total: 1				
Property Type			Number		
Application Number: 141		14190885	190885		
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Total Attachments: 2

Signature:

Date:

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502701668 PATENT REEL: 032324 FRAME: 0996

/Terryence F. Chapman/

02/28/2014

United States (Sole or Joint) (Excluding Foreign Rights)

Docket No.: 4700.P0401US U.S. Serial No.: 14/190 885 U.S. Filing Date: February 26, 2014

## ASSIGNMENT

WHEREAS, I/We, (1) Hiroshi INOUE, (2) Akio KATSUMATA, (3) Shigenori SAWACHI and (4) Osamu YAMAGATA

Residing at (1) Yokohama-shi, Kanagawa, Japan;

(2) Yokohama-shi, Kanagawa, Japan;

(3) Yokohama-shi, Kanagawa, Japan and

(4) Yokohama-shi, Kanagawa, Japan;

have invented certain new and useful improvements in

SEMICONDUCTOR DEVICE, SEMICONDUCTOR STACKED MODULE STRUCTURE, STACKED MODULE STRUCTURE AND METHOD OF MANUFACTURING SAME

for which an application for United States Letters Patent was filed on February 26, 2014 and received PCT Application No. or U.S. Serial No. 14/190 885

WHEREAS, J-DEVICES CORPORATION

having a place of business at 1913-2, Fukura, Usuki-shi, Oita, Japan

hereinafter called the "Assignee", is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefor, in the United States and its territorial possessions.

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) and other valuable considerations, the receipt whereof is hereby acknowledged, I/we have sold, assigned and transferred, and by these presents do sell, assign, transfer and confirm in and to said Assignee my/our full and exclusive right to the said invention in the United States and its territorial possessions and my/our entire right, title and interest in and to said application and any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in and to any and all divisions, reissues, continuations and extensions thereof.

I/We hereby authorize and request the Patent Office Officials in the United States to issue any and all of said Letters Patent, when granted, to said Assignee for the sole use and behoof of the said Assignee, its successors and assigns.

I/We hereby authorize and request the attorneys of record to insert in this Assignment the filing date and serial number of the above-referenced United Sates application when officially known.

IN TESTIMONY WHEREOF, I/We have hereunto set my/our hand(s).

**PATENT** REEL: 032324 FRAME: 0997 Witnessed by:

Kohei Inada

Inventors:

Date:

Hiroshi INOUE February 10, 2014

Akio katsumata February 10, 2014
Akio KATSUMATA

Shigenori Sawachi February 10, 2014
Shigenori SAWACHI

Osamu YAMAGATA

Desamu YAMAGATA

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**RECORDED: 02/28/2014** 

PATENT REEL: 032324 FRAME: 0998